



NIC COMPONENTS CORP.

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REFLOW SOLDERING HEAT LIMITS
SMT Magnetics Products

Product Series	Preheat: 150°C~180°C	MAX SOLDERING TEMPERATURE*	MAX EXPOSURE TIME AT MAX SOLDERING TEMPERATURE	MAX EXPOSURE TIME ABOVE REFERENCE TEMPERATURE	Multiple Reflow Exposure
NCB NCB-H NCC NIN-Hx NIN-FB NLQ NML NFI NPI NPIS	120 seconds Max.	+260°C	10 seconds	60 seconds Max. above +230°C	2 Times Max.
NIS	120 seconds Max.	+260°C	10 seconds	30 seconds Max. above +230°C 60 seconds Max. above +217°C	2 Times Max.
NIN-FA & FC NIN-Nx NIN-Px	120 seconds Max.	+250°C	10 seconds	30 seconds Max. above +230°C 60 seconds Max. above +217°C	2 Times Max.

* - Top Surface of Component

REFLOW SOLDER LIMITS

